

USB Type-C Connector

1 Scope:

1.1 Contents

This specification covers the requirements for product performance, test methods and quality assurance provisions of TE Connectivity USB type C connector.

Applicable product description and part numbers are as shown in Appendix 1.

2. Applicable Documents:

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1 TE Connectivity Specification:

A. 109-5000: Test Specification, General Requirements for Test Methods

- B. 501-115170: Qualification Test Report
- 2.2 Commercial Standard and Specification:

A. ANSI/EIA 364-C

B. Universal Serial Bus Type-C Connector and Cables Assemblies Compliance Document.

3. Requirements:

3.1 Design and Construction:

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2 Materials:

A. Contact (Plug & Receptacle)

Material: Copper alloy

B. Housing (Plug & Receptacle)

Thermo Plastic, UL 94 V-0

C. Shell (Plug & Receptacle)

Material: Stainless steel

3.3 Ratings:

- A. Voltage Rating: 30 V Max.
- B. Current Rating:
 - (1). VBUS/GND pins: 1.25A Max
 - (2). VCONN pins: 1.25A Max.
 - (3). Signal pins contact: 0.25A Min.
- C. Temperature Rating: -40°C to 85°C (Including temperature rising)
- D. Storage Temperature: -40°C to 85°C

3.4 Performance Requirements and Test Descriptions:

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig.1. All tests shall be performed in the room temperature, unless otherwise specified.

Temperature:15°C ~ 35°C Humidity :25% ~ 85% R.H. Pressure :650mmHg ~ 800mmHg

| DR Rambo Zhang | | DATE 18-Jan-2019 | APVD Simon Li | DATE 18-Jan-2019 |
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3.5 Test Requirements and Procedures Summary

Table.1

| Test Item | Procedures | Requirements |
|--|---|--|
| | Examination | |
| Visual examination of product | EIA 364-18. Visual, dimensional and functional meets requirements of product drawing and applicable instructions on customer drawing, and application specification. | Meets requirements of product drawing and no defects. |
| Electrical | | |
| Low Level Contact Resistance | EIA 364-23 The low-level contact resistance (LLCR) measurement is made across the plug and receptacle mated contacts and does not include any internal paddle cards or substrates of the plug or receptacle. See Figure 1 Measure at 20mV (max) open circuit at 100 mA | 40 mΩ (Max) initial for VBUS, GND and all other contacts. Maximum change (delta) of +10 mΩ after environmental stresses. |
| Dielectric Withstanding Voltage | EIA-364-20, Method B. Applicable to both receptacle and plug. 100VAC (rms) for 1 minute at sea level. | No break down shall occur when voltage is applied between adjacent contacts of unmated and mated connectors |
| Insulation Resistance | EIA 364-21 Applicable to both receptacle and plug. Apply 500V DC Apply the above specified voltage between adjacent contacts for 2 minutes. | >100 MΩ insulation resistance between adjacent contacts of unmated and mated connectors |
| Current Rating | EIA 364-70, Method 2. See USB Type C Compliancy Document Appendix C. A current of 5.0 A shall be applied collectively to VBUS pins (i.e., pins A4, A9, B4, and B9) and 1.25 A applied to the VCONN pin (i.e., B5 of the plug connector) with the return path through the corresponding GND pins (i.e., pins A1, A12, B1, and B12). A minimum current of 0.25 A shall also be applied individually to all the other contacts. Allow to stabilize. Note: special T-rise test boards design per the guidelines in Appendix C of the USB Type C Compliancy Document are to be used. | Temperature rise of the outside shell surface of the mated connector pair above the VBUS and GND contacts shall not exceed 30°C above ambient temperature. |
| Mechanical | | |
| Critical Dimension Inspection ¹ | See USB Type C Compliancy Document Appendix B. | Meet all critical dimension requirements defined in Appendix B. |
| Insertion Force | EIA-364-13 Maximum rate 12.5mm/min | Between 5N and 20N before and after durability. |
| Extraction Force | EIA-364-13 Maximum rate 12.5mm/min | Within the range of 8 N to 20 N, measured after a preconditioning of five insertion/extraction cycles (i.e., the sixth extraction). After an additional twenty-five insertion/extraction cycles, the extraction force shall be measured again (i.e., the thirty-second extraction) and the extraction force shall be within: a) 33 % of the initial reading, and b) within the range of 8 N to 20 N. The extraction force shall be within the range of 6 N to 20 N after 10,000 insertion/extraction cycles. |

¹ Separate Report



| Table.1(END) | | |
|-------------------|---|---|
| Durability | EIA 364-09, 10,000 cycles | No evidence of physical damage |
| Durability | EIA 364-09, 50 cycles | No evidence of physical damage |
| (Preconditioning) | | |
| Reseating | Manually unplug/plug the connector. 3 such cycles. | No evidence of physical damage |
| Environmental | | |
| Temperature Life | EIA-364-17, Method A | No evidence of physical damages |
| | 105°C, 120hrs | Meet LLCR requirement |
| | | Insulation > 100M Ω Min. |
| Temperature Life | EIA-364-17, Method A | No evidence of physical damages |
| (Preconditioning) | 105°C, 72hrs | Meet LLCR requirement |
| | | Insulation > 100M Ω Min. |
| Thermal Shock | EIA-364-32, Method A, Condition I, duration A-4 | No evidence of physical damages |
| | (-55°-+85°C, 10 cycles) | Meet LLCR requirement |
| | | Insulation > 100M Ω Min. |
| Cyclic | EIA-364-31, Method III, w/o optional cold shock and | No evidence of physical damages |
| Temperature and | vibration. | Meet LLCR requirement |
| Humidity | Exceptions per EIA-364-1000: | Insulation > 100M Ω Min. |
| | - Cycle between 25°C/80%RH and 65°C/50%RH. | |
| | - Ramp 0.5hr, dwell 1hr, dwell starts when conditions | |
| | are stabilized. | |
| | - 24 cycles total | |
| | Allowable variation ±3°C and ±3%RH | |
| Vibration | EIA-364-28, Condition VII-D, 15min in each of 3 | No evidence of physical damages and no |
| | mutually perpendicular directions. Both mating | discontinuity longer than 1 microsecond. |
| | halves should be fixed rigidly. | |
| | (Power Spectral Density 0.02g ² /Hz, Overall rms 3.10g) | |
| Mixed Flowing | EIA-364-65, class IIA, 112hrs unmated, 56hrs mated | No evidence of physical damages |
| Gas | (168hrs total). | Meet LLCR requirement |
| | | Insulation > 100M Ω Min. |
| Thermal | Cycle the mated connector pair 10 times between | No evidence of physical damages |
| Disturbance | 15°C and 85°C. | Meet LLCR requirement |
| | - ramp > 2°C/min | Insulation > 100M Ω Min. |
| | dwell > 5 mins (ensure contacts reach temperature) | |
| | - Humidity not controlled | |
| Other | | |
| Solderability | Category 3 Steam Age RMA Class 1 flux immerse in | Solderable area shall have a minimum of 95% |
| | molten solder at a temperature of $+255^{\circ}C \pm 5^{\circ}C$ at | solder coverage. |
| | rate of 25.4 mm \pm 6.35 mm per second. Hold in | |
| | solder for 5 +0/-0.5 seconds. To include solder pins | |
| | and mounting pads. | |

NOTE: (1) Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Prequalification Test Sequence shown in table 2.



108-115153

3.6 Product Qualification Test Sequence

Table.2

| Test | A-1 | A-2 | A-3 | A-4 | A-7 | B-5 ² | B-6 | C-1 ³ |
|-----------------------|-------|---------|-------|---------|-----|------------------|-----|------------------|
| Critical Dimensions | | | | | | 1 | | |
| Low Level Contact | 1,4,6 | 1169 | 1,4,6 | 1169 | 2,7 | | | |
| Resistance | 1,4,0 | 1,4,6,8 | 1,4,0 | 1,4,6,8 | 2,7 | | | |
| Durability | | | | | 5 | | | |
| Durability | 2 | 2 | 2 | 2 | | | | |
| (Preconditioning | 2 | 2 | 2 | 2 | | | | |
| Insertion Force | | | | | 3 | | | |
| Extraction Force | | | | | 4,6 | | | |
| Temperature Life | 3 | | | 3 | | | | |
| Temperature Life | | | 3 | | | | | |
| (Preconditioning) | | | 5 | | | | | |
| Reseating | 5 | 7 | | | | | | |
| Thermal Shock | | 3 | | | | | | |
| Cyclic Temperature | | 5 | | | | | | |
| and Humidity | | 5 | | | | | | |
| Vibration | | | 5 | | | | | |
| Mixed Flowing Gas | | | | 5 | | | | |
| Thermal Disturbance | | | | 7 | | | | |
| Dielectric | | | | | 10 | | | |
| Withstanding Voltage | | | | | 1,8 | | | |
| Insulation Resistance | | | | | 9 | | | |
| Current Rating | | | | | | | 1 | |
| Solderability | | | | | | | | 1 |
| Sample Size | 5 | 5 | 5 | 5 | 5 | 5 | 5 | 5 |

Signal Integrity Testing

The following cable assembly specific test groups are to be reported in a separate test report:

- Test Group B-5: Refer to product drawing.

Test Requirements and Test Sequence as per USB Type C Compliance Document.

² To be reported in Critical Dimension Inspection Report

³ Additional test, not part of USB Type C Compliance Requirements



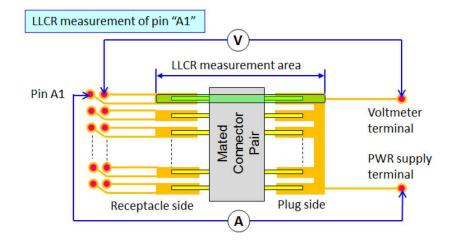


Figure 1: Typical Contact Resistance Measurement

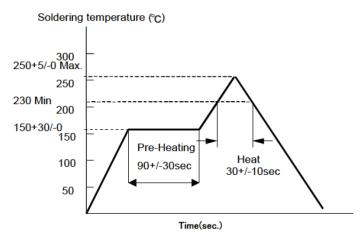


Figure 2. Recommended reflow temp profile



The applicable product descriptions and part numbers are as shown in Appendix.1.

| Product Part No. | Description | | | |
|------------------|--|--|--|--|
| 2345986-* | USB TYPE C 3.1 CONN REC. TOP MOUNT DUAL ROW SMT TYPE WITH 1.63 OFFSET | | | |

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|---------------|-------------|----------------------------|
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| LTR | REVISION RECORD | ECN | DR | CHK | APP | DATE |
|-----|------------------------|-----|------|------|------|-------------|
| А | RELEASED | | R. Z | R. M | S. L | 13-MAY-2019 |
| В | RELEASED | | AK | SZ | SZ | 09-JUN-2022 |
| С | RELEASED | | AK | SZ | SZ | 29-JUN-2022 |